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(71) Applicant: **VERSUM MATERIALS US, LLC** [US/US];
8555 South River Parkway, Tempe, Arizona 85284 (US).

(72) Inventors: **MCBRIARTY, Martin**; c/o Versum Materials US, LLC, 8555 South River Parkway, Tempe, Arizona 85284 (US). **VU, Nguyen**; c/o Versum Materials US, LLC, 8555 South River Parkway, Tempe, Arizona 85284 (US). **ZOPE, Bhushan**; c/o Versum Materials US, LLC, 8555 South River Parkway, Tempe, Arizona 85284 (US).

(74) Agent: **SLAVEN IV, William T.**; Versum Materials US, LLC, 8555 South River Parkway, Tempe, Arizona 85284 (US).

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(54) Title: VAPOR-PHASE ETCH OF METAL-CONTAINING MATERIALS

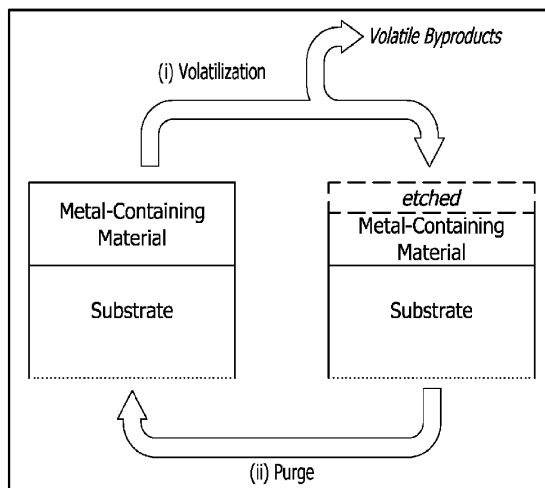


FIG. 1

(57) **Abstract:** The disclosed and claimed subject matter relates to processes for performing selective thermal vapor-phase etching of metals, including Ti, Co, Ni, Cu, Mo, Ru, Ta and/or W, and compounds thereof, such as oxides, hydroxides, oxyhydroxides, carbonates, carbides, fluorides, or chlorides, which do not require the use of plasmas or halogenated volatilizing agents.

[Continued on next page]

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